

For Immediate Release

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KOKI Solder America to Highlight Solder Paste Performance and Process Research at SMTA International 2026



Blue Ash, OH – October 13, 2026 – KOKI Solder America Inc. will exhibit at SMTA International 2026, taking place October 25–29 at the Donald E. Stephens Convention Center in Rosemont, Illinois. At Booth #2634, the company will showcase soldering materials designed to help electronics manufacturers improve assembly performance, reliability and process efficiency.

KOKI's exhibit will feature two low-silver, lead-free solder pastes developed to reduce silver content while maintaining the performance required for demanding surface-mount technology (SMT) applications. These halogen-free materials offer ultra-low voiding, strong wettability, stable printability and excellent solder joint reliability.

The company will also highlight S3X58-HF1200, a SAC305 solder paste designed to address multiple SMT assembly challenges. The HF1200 platform combines low voiding, strong wettability and stable printing performance with a wide process window and halogen-free formulation.

Alongside its exhibit, KOKI will highlight three technical presentations addressing solder alloy reliability, ultra-high-density printing and stencil cleaning intervals:

- “Reliability Evaluation of Low-Silver Solder Alloy Solder Paste” — Shantanu Joshi, KOKI Solder America Inc.; Tuesday, October 27, 4:00–4:30 p.m. CDT.
- “Solder Powder Size Types and Their Associated Print Capabilities in Ultra High Density Applications” — Chrys Shea, Shea Engineering Services; Tuesday, October 27, 4:30–5:00 p.m. CDT.
- “Evaluation of Solder Paste Printability with Solder Paste Inspection Equipment After Extended Stencil Cleaning Cycle Intervals” — Shantanu Joshi, KOKI Solder America Inc.; Wednesday, October 28, 2:30–3:00 p.m. CDT.

These presentations will examine material selection and printing considerations relevant to manufacturers working to improve process consistency and assembly reliability.

Visitors are invited to meet with the KOKI team at Booth #2634 to discuss their soldering requirements and explore materials suited to their applications. For more information about KOKI's soldering solutions, visit koki-global.com. Event information is available at smtai.org.

KOKI SOLDER AMERICA, INC.

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About KOKI

Founded in 1964, KOKI leads in advanced soldering materials, emphasizing innovation, sustainability, and compliance. Beyond products, KOKI provides comprehensive technical support, including analytical services and process optimization, to support process optimization and performance. With a global focus, KOKI continues to set new standards in soldering technology and customer support.

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